

**Plasma-Therm Technical Workshop:
Fundamentals of Plasma Processing (Etching)**
University of Alberta, Nanofabrication Laboratory
Room: W2-021, Bldg. ECERF
1 October 2013 (Tuesday), 8:00am to 12:00pm

Plasma-Therm, a leading manufacturer of plasma based etching and deposition equipment, is providing a workshop focusing on the fundamentals of plasma etching. Lectures will include basics of plasma etching mechanisms with relevant examples relating to compound semiconductor, dielectric, metal, and deep silicon etching. State-of-the-art etching technologies for deep silicon will be reviewed. Fundamental and new ideas for endpoint detection and sample thermal budget management will be presented.



Registration is free, however online pre-registration by 30 September 2013 is requested at <http://www.planetReq.com/E9178114518136>

For general and registration inquiries, please contact:
Mr. Scott Munro Tel: 587-879-1517 Email: smunro@ualberta.ca

Objectives

- Learn the fundamentals etching mechanisms
- Review current etching technologies for deep silicon etching
- Explore the fundamentals and new ideas in endpoint detection
- Understand thermal budget considerations

Program

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| 7:30 am - 8:00 am | Registration and light breakfast (provided by Plasma-Therm) |
| 8:00 am - 8:15 am | Welcome |
| 8:15 am - 9:15 am | Plasma Etching Mechanisms |
| 9:15 am - 9:30 am | Break |
| 9:30 am - 10:30 am | Deep Silicon Etching |
| 10:30 am - 10:45 pm | Break |
| 10:45 pm - 11:15 pm | Endpoint Basics |
| 11:15 pm - 11:45 pm | Thermal Budget Management |
| 11:45 pm - 12:00 pm | Q&A |

Continental breakfast will be provided
Speaker information follows:

Speaker Information: David Lishan, Ph.D.



David Lishan received his Bachelor's degree in Chemistry from UC, Santa Cruz and M.S. and Ph.D. from UC, Santa Barbara in Solid State Electrical Engineering. During his career he has worked and published on wide range of material, semiconductor, and chemistry R&D projects in the areas of photochemistry, x-ray mask fabrication, PVD, and plasma processing. He joined Plasma-Therm 15 years ago and currently holds the position of Principal Scientist and Director in the Technical Marketing Group. His primary focus is on the application of plasma processing for MEMS, photonics, data storage, and compound semiconductor applications. He holds two patents in the area of semiconductor processing and over 60 publications and conference presentations.

Plasma-Therm has recently organized and presented plasma processing workshops at Harvard University, UC Berkeley, University of Notre Dame, UC Los Angeles (UCLA), University of South Florida, Stanford University, Lund University (Sweden), IMRE (Singapore), UC Santa Barbara (UCSB), ISCAS (Beijing, China), SINANO (Suzhou, China), UT Austin, Cornell University, Korea Advanced Nanofabrication Center (KANC), Penn State and in Israel.